TOSHIBA FIELD EFFECT TRANSISTOR SILICON N CHANNEL MOS TYPE (U-MOS)

2 S K 3 0 8 4

HIGH SPEED, HIGH CURRENT SWITCHING APPLICATIONS CHOPPER REGULATOR, DC-DC CONVERTER AND MOTOR DRIVE **APPLICATIONS**

4 V Gate Drive

Low Drain-Source ON Resistance : $R_{DS(ON)} = 40 \text{ m}\Omega$ (Typ.)

High Forward Transfer Admittance : $|Y_{fS}| = 27 \text{ S}$ (Typ.)

Low Leakage Current : $I_{DSS} = 100 \,\mu\text{A}$ (Max.) ($V_{DS} = 100 \,\text{V}$)

Enhancement-Mode : $V_{th} = 0.8 \sim 2.0 \text{ V}$

 $(V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA})$

MAXIMUM RATINGS (Ta = 25°C)

CHARACTERI	SYMBOL RATING		UNIT					
Drain-Source Voltage	$v_{ m DSS}$	100	V					
Drain-Gate Voltage (R	$v_{ m DGR}$	100	V					
Gate-Source Voltage	v_{GSS}	±20	V					
DOD	DC	${ m I}_{ m D}$	30	A				
DCDrain Current	Pulse	${ m I_{DP}}$	120	A				
Drain Power Dissipation	$P_{\mathbf{D}}$	65	W					
Single Pulse Avalanche	EAS	293	mJ					
Avalanche Current	I_{AR}	30	A					
Repetitive Avalanche I	$\mathbf{E_{AR}}$	6.5	mJ					
Channel Temperature	$\mathrm{T_{ch}}$	150	°C					
Storage Temperature R	${f T_{stg}}$	-55~150	°C					

THERMAL CHARACTERISTICS

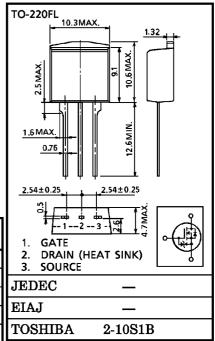
CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	$R_{ m th\ (ch-c)}$	1.92	°C/W
Thermal Resistance, Channel to Ambient	R _{th (ch-a)}	83.3	°C/W

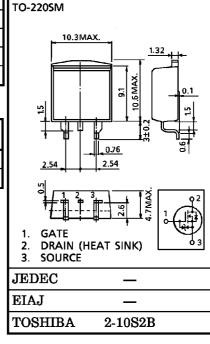
Note;

- * Repetitive rating; Pulse Width Limited by Max. junction temperature.
- ** $\rm V_{DD} = 25\,V, \, T_{ch} = 25^{\circ}C$ (initial), $\rm L = 525\,\mu H$ $R_G = 25 \Omega$, $I_{AR} = 30 A$

This transistor is an electrostatic sensitive device. Please handle with caution.

INDUSTRIAL APPLICATIONS Unit in mm





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ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARA	CTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage	e Current	IGSS	$V_{GS} = \pm 16 V, V_{DS} = 0 V$		_	±20	μA
Drain Cut-off		IDSS	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	100	$\mu \mathbf{A}$
Drain-Source Voltage			$I_{D} = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	100	_	_	v
Gate Thresho	old Voltage	v_{th}	$V_{\mathrm{DS}} = 10 \mathrm{V}, \; \mathrm{I}_{\mathrm{D}} = 1 \mathrm{mA}$	0.8	_	2.0	V
Drain-Source	ON Resistance	R _{DS} (ON)	$V_{GS} = 4 \text{ V}, I_D = 15 \text{ A}$ $V_{GS} = 10 \text{ V}, I_D = 15 \text{ A}$	_	46 40	70 46	$\mathbf{m}\Omega$
Forward Tran Admittance	nsfer	Y _{fs}	$V_{DS} = 10 \text{ V}, I_{D} = 15 \text{ A}$	13	27	_	S
Input Capacit	Input Capacitance			_	3250	_	
Reverse Transfer Capacitance		C _{iss}	$V_{ m DS} = 10 m V, \ V_{ m GS} = 0 m V, \ f = 1 MHz$	_	230	_	pF
Output Capacitance		Coss		_	520	_	
Switching Time Fall Ti	Rise Time	t _r	$V_{GS}^{10 \text{ V}} V_{GS}^{10 \text{ V}} V_{OUT}$ $R_{L} = 3.33 \Omega$ $V_{DD} = 50 \text{ V}$ $V_{IN} : t_r, t_f < 5 \text{ ns,}$ $Duty \leq 1\%, t_w = 10 \mu \text{s}$	_	33	_	
	Turn-on Time	t _{on}		_	60	_	ns
	Fall Time	tf		_	95		ns
	Turn-off Time	t _{off}		_	230		
Total Gate Charge (Gate- Source Plus Gate-Drain)		$\mathbf{Q}_{\mathbf{g}}$	$V_{DD} = 80 \text{ V}, V_{GS} = 10 \text{ V},$	_	68	_	nC
Gate-Source Charge		$egin{array}{c} Q_{ m gs} \ Q_{ m gd} \end{array}$	$I_D = 30 A$	_	46	_] "
Gate-Drain (Gate-Drain ("Miller") Charge			_	22	_	

SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	$I_{ m DR}$	_	_	_	30	A
Pulse Drain Reverse Current	$I_{ m DRP}$	_	_	_	120	A
Diode Forward Voltage	$v_{ m DSF}$	$I_{DR} = 30 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.7	V
Reverse Recovery Time	$\mathfrak{t}_{ extbf{rr}}$	$I_{\mathrm{DR}} = 30 \mathrm{A}, \mathrm{V}_{\mathrm{GS}} = 0 \mathrm{V}$		140	_	ns
Reverse Recovery Charge	$Q_{\mathbf{rr}}$	$dI_{DR}/dt = 50 A/\mu s$	_	370	_	nC

MARKING

